

■ Features

- Molding Inductor.
- Low Profile, Low Temp.
- Large Current (Over 15A).
- Customize For Different Need.
- Operating temperature: $-25^{\circ}\text{C} \sim +125^{\circ}\text{C}$.

■ Applications

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.

■ Product Identification

YSPI □□□□ — □□□ □ □□
(1) (2) (3) (4) (5)

(1) : Type

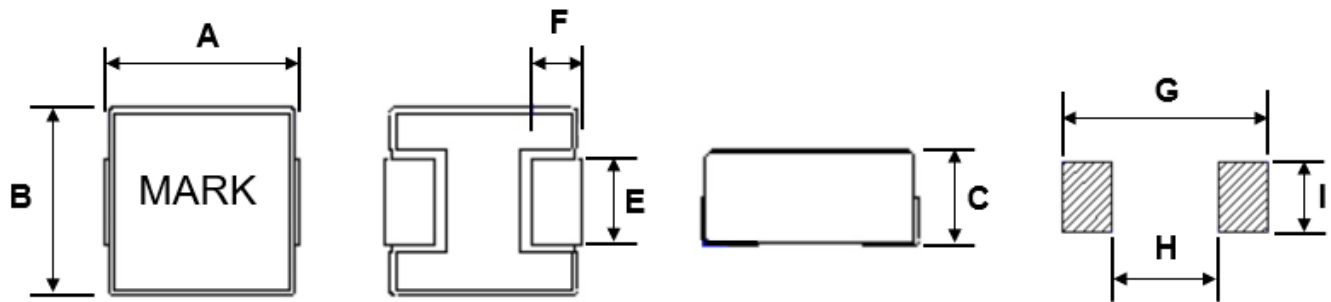
(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N=±30%, M=±20%

(5) : Lettering mark

■ Shapes and Dimensions (Unit: mm)



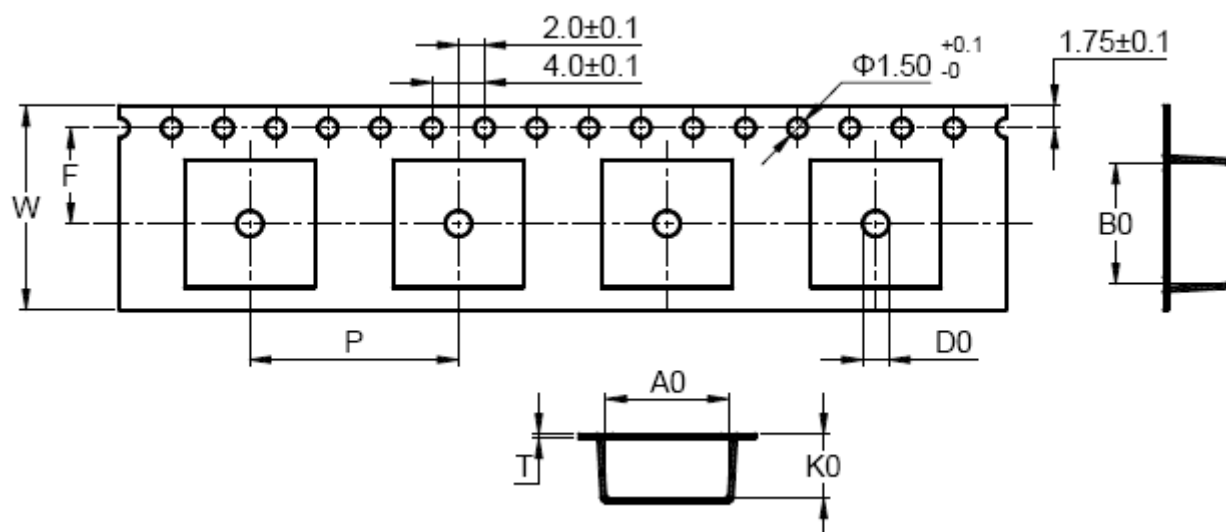
TYPE	A	B	C Max.	E	F	G Ref.	H Ref.	I Ref.
YSPI0420	4.3±0.5	4.0±0.2	2.0	1.5±0.5	0.8±0.5	5.2	2.2	2.5

■ Electrical characteristics

Part Number	Inductance (uH) 100KHz	DCR Max. (mΩ)	Heat Rating Current (A)	Saturation Current (A)
YSPI0420-1R5MGG	1.5±20%	36	4.0	6.0

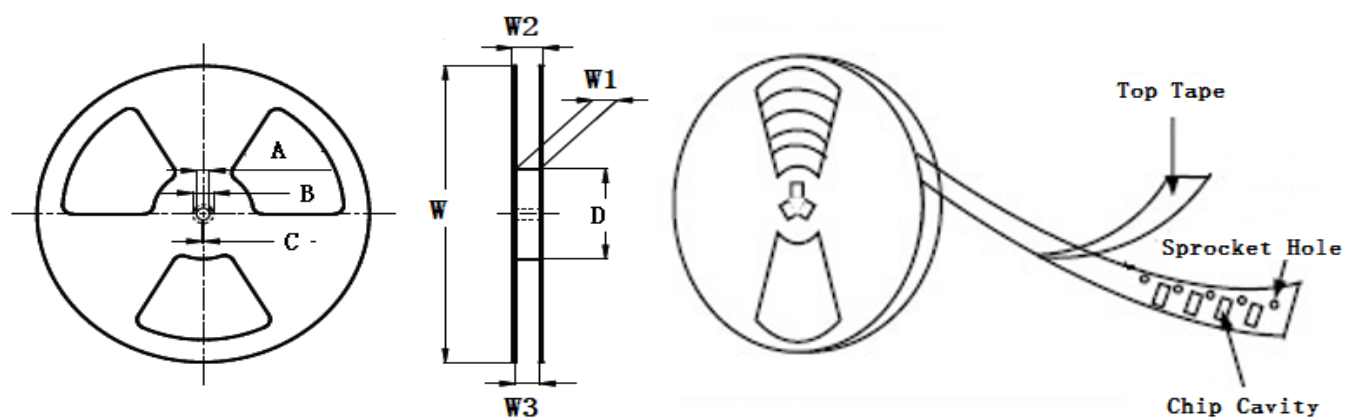
- ※ The saturation current value is the DC current value having inductance decrease down to 35%.(at 20℃)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40℃. (at 20℃)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

■ Taping Dimensions(Unit:mm)



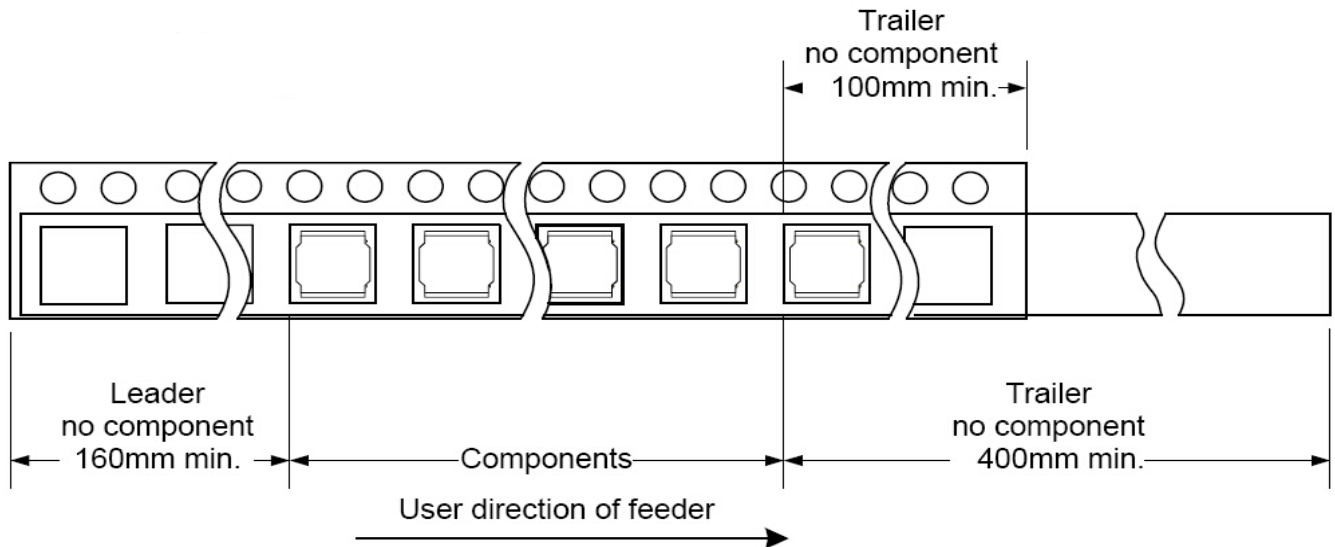
TYPE	W	A0	B0	K0	P	F	T	D0	MPQ
YSPI0420	12±0.3	4.5±0.1	4.85±0.1	2.1±0.1	8.0±0.1	5.5±0.1	0.4±0.05	1.5±0.1	3000

■ Reel Dimensions(Unit:mm)

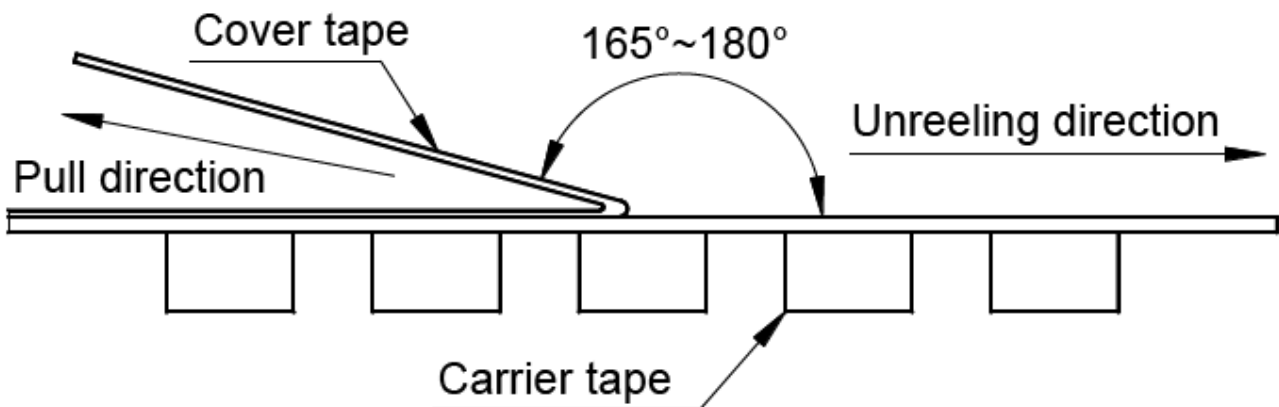


TYPE	W	W1	W2	W3	A	B	C	D
YSPI0420	330±2.0	12.4±2.0	18.4MAX	11.9 Min	13.0±0.50	21.0±0.80	2.0±0.50	100 Min

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300 ± 10 mm/min.